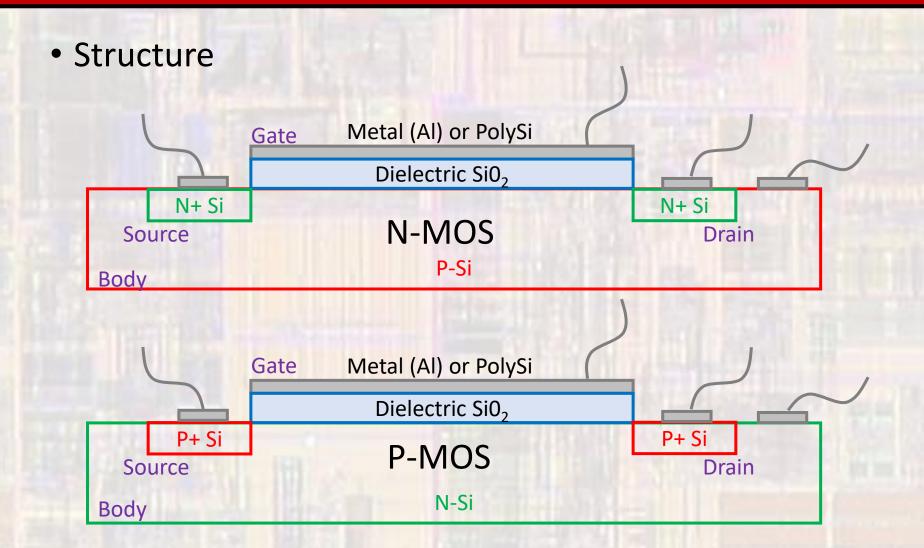
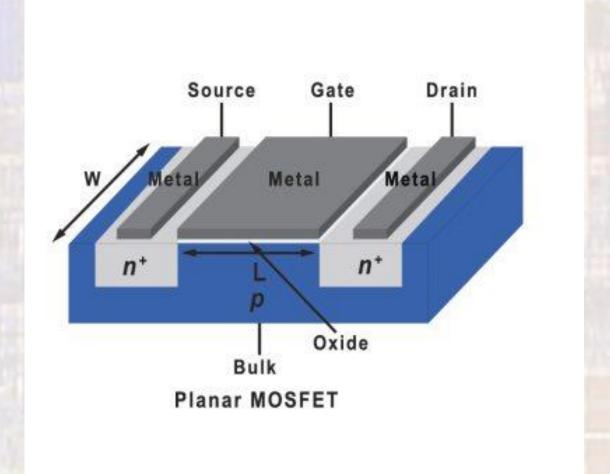
Metal Oxide Semiconductor Enhancement Mode Transistor

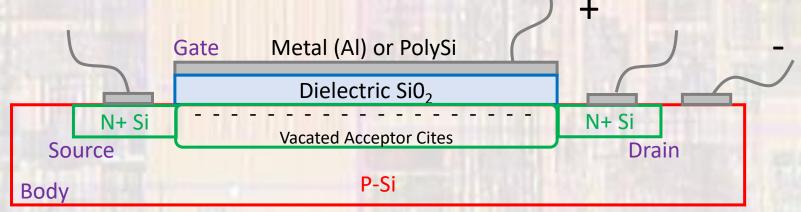
Last updated 3/24/22



Structure

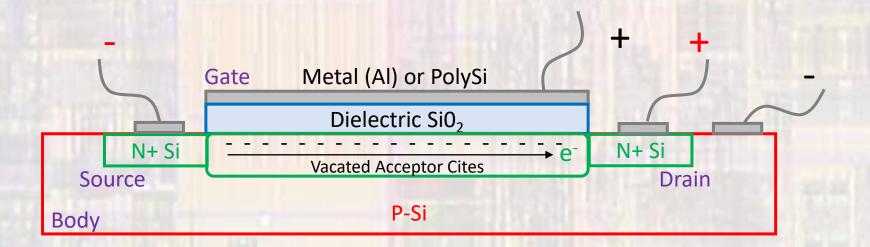


- N-MOS Operation
 - Large Positive Bias
 - Depletion region is formed
 - Mobile holes pushed away (region is depleted of holes)
 - Net negative (fixed) charge left behind
 - Electrons are drawn from the Si to form an inversion layer



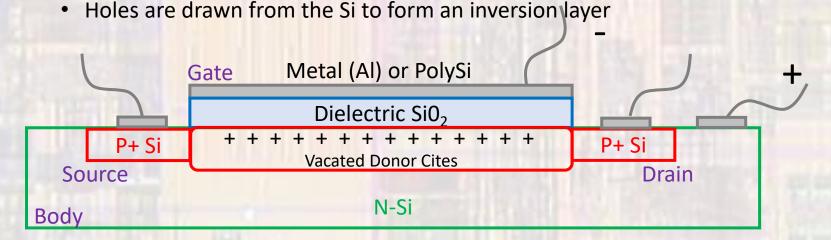
A channel is formed from Source to Drain Electrons can flow through this channel

- N-MOS Operation
 - Large Positive Bias + Positive Bias from Drain to Source
 - Electrons move from Source to Drain
 - Current flows from Drain to Source



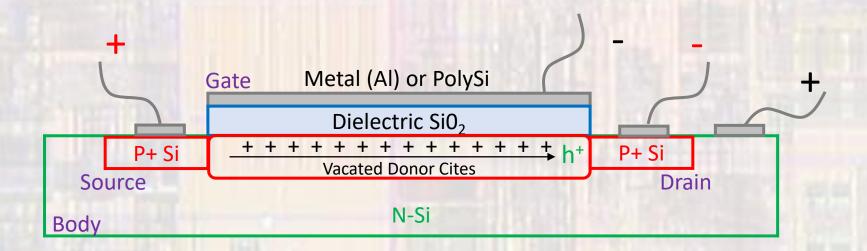
P-MOS Operation

- Large Negative Bias
 - Depletion region is formed
 - Mobile electrons pushed away (region is depleted of electrons)
 - Net positive (fixed) charge left behind



A channel is formed from Source to Drain Holes can flow through this channel

- P-MOS Operation
 - Large Negative Bias + Positive Bias from Source to Drain
 - Holes move from Source to Drain
 - Current flows from Source to Drain



- Enhancement Mode
 - A bias is required to form the channel
 - 4-terminal symbol





- In digital applications the Source is typically tied to
 - Vdd for P-MOS
 - Gnd for N-MOS





The simplified logic symbols





Note – almost all N-MOS and P-MOS devices used today are enhancement mode – so the dashed line is omitted

Parameters

- W width of the transistor
- L length of the transistor (S to D)
- V_{th} threshold voltage (inversion layer formed)
- Kn, Kp conduction parameter

$$K_n = \frac{W\mu_n C_{ox}}{2L} \qquad K_p = \frac{W\mu_p C_{ox}}{2L}$$

$$K_n = \frac{k'_n}{2} \frac{W}{L}$$

$$K_p = \frac{k'_p}{2} \frac{W}{L}$$

$$k'_n = \mu_n C_{ox}$$

$$k'_p = \mu_p C_{ox}$$

 μ_n , μ_n , C_{ox} fixed for a given semiconductor process